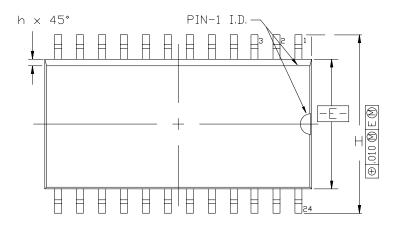
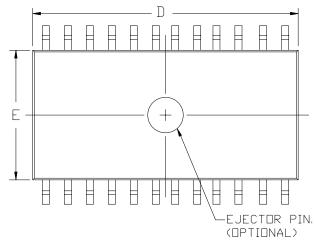
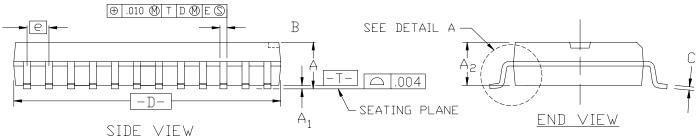
## SOIC (SO24) Package

## TOP VIEW

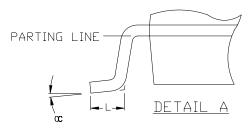
## BOTTOM VIEW







S M B	INCHES		
L	MIN.	NDM,	MAX.
A	.097	.101	.104
$A_1$	.005	,009	.0115
A <sub>2</sub>	.090	.092	.094
В	.014	.016	.019
C	.0091	.010	.0125
	.600	,605	.610
E	.292	.296	.299
0	.050 BSC		
H	.400	.406	.410
h	.010		.029
L	.024	.032	.040
$\propto$	0 *	5*	8*



## NOTES:

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
- 2. DIMENSION "D" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
- 3. DIMENSION "E" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .010" PER SIDE.
- 4. LEAD FINISH: SOLDER PLATE
- 5. CONFORMS TO JEDEC MS-013-AD

24-LEAD SOIC (SO24)

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